REV 0  ISSUED S.M.S.M.B.S. 07/29/15

SMP TECHNOLOGY, INC.

SCALE

TOL. DEC. .X +/- 0.25 .XX +/- 0.20 ANGLE +/- 5° UNIT: mm

SERIES: UX05-0200-10X2-Z

Isometric View

USB 3.1 Receptacle, Type C Surface Mount with (11.75mm) Thru Hole Shell Legs, 2.18mm Offset

How To Order:

- U X 0 5 - 0 2 0 0 - 1 0 X 2 - Z

Body Style

0 - Female Right Angle

# of Positions

02 - 24 Position SMT

Mounting Style

00 - Surface Mount Thru Hole Shell Legs

Offset

1 - 2.18mm

Contact Area Plating

Gold Plating over 50u" Nickel on Contact Area, 80u" Tin Plating over 50u" Nickel on Solder Area

Shell: Stainless Steel with 50u" Nickel Plating

Material

INSULATOR: LCP, UL94V-0, Black / Blue
CONTACTS: Copper Alloy
CONTACT PLATING:
- Gold Plating over 50u" Nickel on Contact Area,
- 80u" Tin Plating over 50u" Nickel on Solder Area

Mechanical

INSERTION FORCE: 5 – 20N Max.
WITHDRAWAL FORCE: 8 – 20N Kg
DURABILITY: 10000 Cycles

Insertion Force: 5 ~ 20N Max.
Withdrawal Force: 8 ~ 20N Kg
Durability: 10000 Cycles

Electrical

CURRENT RATING: 5A Min. for VBUS,
0.25A Min. for Other

CONTACT RESISTANCE:
< 20 Milliohm Max.

INSULATION RESISTANCE:
> 1000 Mgeomn Min.

DIELECTRIC WITHSTANDING VOLTAGE:
100 VAC for 1 Minute

Recommended PCB Layout

Recommended PCB Layout

Signal Name Pin Mating Sequence Signal Name Pin Mating Sequence
A1 GND First B12 GND First
A2 SSTXp1 Second B11 SSTRx1 Second
A3 SSTx1 Second B10 SSTRx1 Second
A4 VBUS First B9 VBUS First
A5 CC1 Second B8 SBU2 Second
A6 Dp1 Second B7 Dn2 Second
A7 Dn1 Second B6 Dp2 Second
A8 SBU1 Second B5 CC2 Second
A9 VBUS First B4 VBUS First
A10 SSTRx2 Second B3 SSTRx2 Second
A11 SSTx2 Second B2 SSTx2 Second
A12 GND First B1 GND First
SHELL GND First Shell GND

Shell Legs, 2.18mm Offset

SMP TECHNOLOGY, INC.

USB 3.1 Receptacle, Type C Surface Mount with (11.75mm) Thru Hole

SHELL GND First Shell GND

Contact Area Plating

RoHS Compliant